

Silicon Carbide (SiC) **Schottky Diode** - EliteSiC, 15 A, 1200 V, D1, TO-247-2L

FFSH15120A

Description

Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size & cost.

Features

- Max Junction Temperature 175°C
- Avalanche Rated 145 mJ

- No Reverse Recovery/No Forward Recovery

 This Device is Pb–Free, Halogen Free/BFR Free and RoHS Compliant

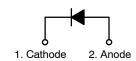
 Applications

 General Purpose

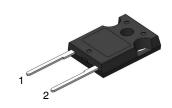
 SMPS, Solar Inverter, UPS

 Power Switching Circuits

 A YWW ZZ FFSH15120A



Schottky Diode



TO-247-2LD CASE 340CL

MARKING DIAGRAM



= Assembly Plant Code = Date Code (Year & Week)

= Lot Code

= Specific Device Code

ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

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FFSH15120A

ABSOLUTE MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit	
V_{RRM}	Peak Repetitive Reverse Voltage	1200	V	
E _{AS}	Single Pulse Avalanche Energy (Note 1)	145	mJ	
lF	Continuous Rectified Forward Current @ T _C <	15	Α	
	Continuous Rectified Forward Current @ T _C <	26	А	
I _{F,Max}	Non-Repetitive Peak Forward Surge Current	T _C = 25°C, 10 μs	920	А
		T _C = 150°C, 10 μs	870	А
I _{F,SM}	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	115	Α
I _{F,RM}	Repetitive Forward Surge Current	Half-Sine Pulse, t _p = 8.3 ms	50	Α
P _{TOT}	Power Dissipation	T _C = 25°C	283	W
		T _C = 150°C	47	W
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	√ °C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Symbol	Parameter			Value	Unit
$R_{ heta JC}$	Thermal Resistance, Junction to Case, Max		CO,	0.53	°C/W

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V _F	Forward Voltage	$I_F = 15 \text{ A}, T_C = 25^{\circ}\text{C}$	10-11	1.45	1.75	V
		$I_F = 15 \text{ A}, T_C = 125^{\circ}\text{C}$	0R-11	1.7	2.0	
		$I_F = 15 \text{ A}, T_C = 175 ^{\circ}\text{C}$	5	2.0	2.4	
I _R	Reverse Current	$V_R = 1200 \text{ V}, T_C = 25^{\circ}\text{C}$	ı	ı	200	μΑ
	J. C. W.	V _R = 1200 V, T _C = 125°C	-	-	300	
,		V _R = 1200 V, T _C = 175°C	-	-	400	
Q_C	Total Capacitive Charge	V = 800 V	-	95	-	nC
С	Total Capacitance	V _R = 1 V, f = 100 kHz	-	936	-	pF
	S OFF.	V _R = 400 V, f = 100 kHz	_	86	_	
		V _R = 800 V, f = 100 kHz	_	68	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

ORDERING INFORMATION

Part Number	Top Marking	Package	Packing Method	Quantity
FFSH15120A	FFSH15120A	TO-247-2LD	Tube	30 Units

^{1.} E_{AS} of 145 mJ is based on starting $T_J = 25^{\circ}C$, L = 0.5 mH, $I_{AS} = 24$ A, V = 50 V.

FFSH15120A

TYPICAL CHARACTERISTICS

(T_J = 25°C UNLESS OTHERWISE NOTED)

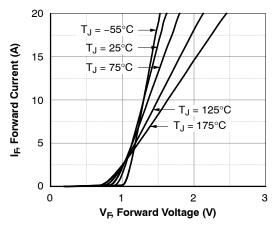


Figure 1. Forward Characteristics

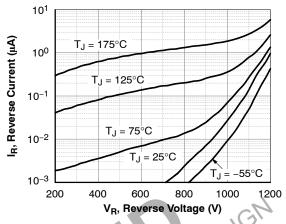
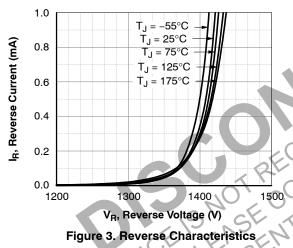


Figure 2. Reverse Characteristics



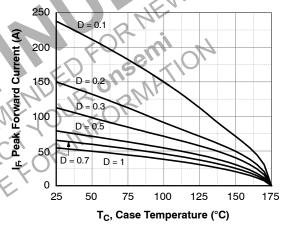


Figure 4. Current Derating

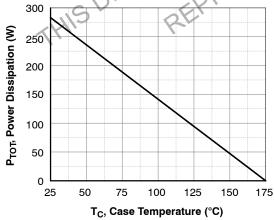


Figure 5. Power Derating

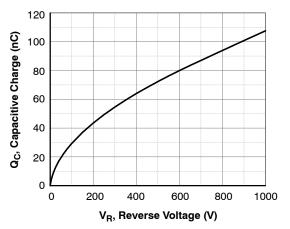


Figure 6. Capacitive Charge vs. Reverse Voltage

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TYPICAL CHARACTERISTICS (CONTINUED)

(T_J = 25°C UNLESS OTHERWISE NOTED)

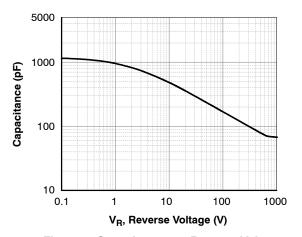


Figure 7. Capacitance vs. Reverse Voltage

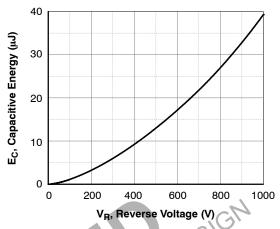


Figure 8. Capacitance Stored Energy

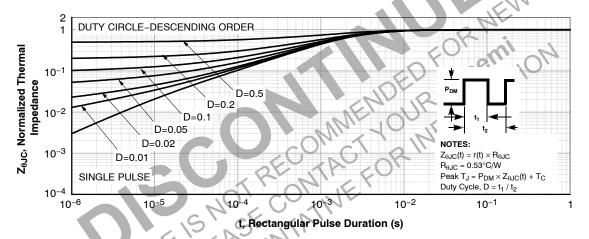
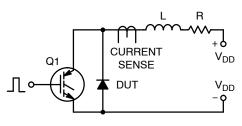


Figure 9. Junction-to-Case Transient Thermal Response Curve

TEST CIRCUIT AND WAVEFORMS

$$\begin{split} L &= 0.5 \text{ mH} \\ R &< 0.1 \ \Omega \\ V_{DD} &= 50 \ V \\ EAVL &= 1/2 LI2 \left[V_{R(AVL)} \ / \ (V_{R(AVL)} - V_{DD}) \right] \\ Q1 &= IGBT \ (BV_{CES} > DUT \ V_{R(AVL)}) \end{split}$$



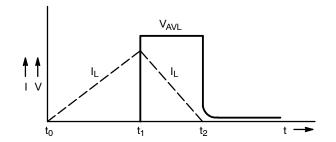
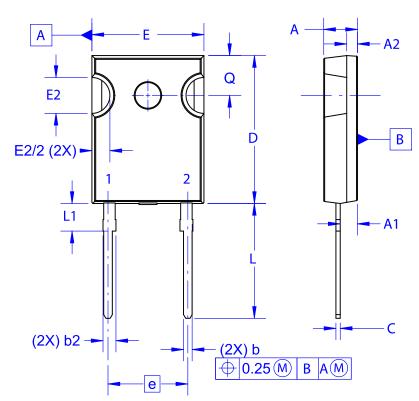


Figure 10. Unclamped Inductive Switching Test Circuit & Waveform

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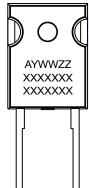






- A. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DRAWING CONFORMS TO ASME Y14.5 2009.
 D. DIMENSION A1 TO BE MEASURED IN THE REGION DEFINED BY L1.
- E. LEAD FINISH IS UNCONTROLLED IN THE REGION DEFINED BY L1.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code

= Assembly Location

= Year

= Work Week WW

= Assembly Lot Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

Ø P —		Ø P1 D2
S E1 —		D1
		J

DIM	MILLIMETERS				
DIM	MIN	NOM	MAX		
Α	4.58	4.70	4.82		
A1	2.29	2.40	2.66		
A2	1.30	1.50	1.70		
b	1.17	1.26	1.35		
b2	1.53	1.65	1.77		
С	0.51	0.61	0.71		
D	20.32	20.57	20.82		
D1	16.37	16.57	16.77		
D2	0.51	0.93	1.35		
Е	15.37	15.62	15.87		
E1	12.81	~	~		
E2	4.96	5.08	5.20		
е	~	11.12	~		
L	15.75	16.00	16.25		
L1	3.69	3.81	3.93		
ØΡ	3.51	3.58	3.65		
Ø P 1	6.61	6.73	6.85		
Q	5.34	5.46	5.58		
S	5.34	5.46	5.58		

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DESCRIPTION:	TO-247-2LD		PAGE 1 OF 1		

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